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TI Copper alloys containing chromium and tin for backing plates for sputtering

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AB The title Cu alloys contain Cr 0.05-1.5; Sn 0.01-0.5; and optionally Zn 0.01-1.0, Mg 0.001-0.5, Co 0.01-1.0, Ni 0.01-0.5, Te 0.02-1.0, and/or Pb 0.01-4.0 weight%. The title Cu alloys have high thermal conductivity, solderability, and heat-warping resistance. Thus, a backing plate of the composition was soldered with an ITO target and repeatedly used in sputtering showing excellent deformation resistance.